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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	22
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-WFQFN Exposed Pad
Supplier Device Package	32-HWQFN (5x5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101beana-u0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101beana-u0</a>

**Table 1-1. List of Ordering Part Numbers**

(6/12)

Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
48 pins	48-pin plastic HWQFN (7 × 7 mm, 0.5 mm pitch)	Mounted	A	R5F100GAANA#U0, R5F100GCANA#U0, R5F100GDANA#U0, R5F100GEANA#U0, R5F100GFANA#U0, R5F100GGANA#U0, R5F100GHANA#U0, R5F100GJANA#U0, R5F100GKANA#U0, R5F100GLANA#U0 R5F100GAANA#W0, R5F100GCANA#W0, R5F100GDANA#W0, R5F100GEANA#W0, R5F100GFANA#W0, R5F100GGANA#W0, R5F100GHANA#W0, R5F100GJANA#W0, R5F100GKANA#W0, R5F100GLANA#W0
			D	R5F100GADNA#U0, R5F100GCDNA#U0, R5F100GDDNA#U0, R5F100GEDNA#U0, R5F100GFDNA#U0, R5F100GGDNA#U0, R5F100GHDNA#U0, R5F100GJDNA#U0, R5F100GKDNA#U0, R5F100GLDNA#U0 R5F100GADNA#W0, R5F100GCDNA#W0, R5F100GDDNA#W0, R5F100GEDNA#W0, R5F100GFDNA#W0, R5F100GGDNA#W0, R5F100GHDNA#W0, R5F100GJDNA#W0, R5F100GKDNA#W0, R5F100GLDNA#W0
			G	R5F100GAGNA#U0, R5F100GCGNA#U0, R5F100GDGNA#U0, R5F100GEGNA#U0, R5F100GFGNA#U0, R5F100GGGNA#U0, R5F100GHGNA#U0, R5F100GJGNA#U0 R5F100GAGNA#W0, R5F100GCGNA#W0, R5F100GDGNA#W0, R5F100GEGNA#W0, R5F100GFGNA#W0, R5F100GGGNA#W0, R5F100GHGNA#W0, R5F100GJGNA#W0
		Not mounted	A	R5F101GAANA#U0, R5F101GCANA#U0, R5F101GDANA#U0, R5F101GEANA#U0, R5F101GFANA#U0, R5F101GGANA#U0, R5F101GHANA#U0, R5F101GJANA#U0, R5F101GKANA#U0, R5F101GLANA#U0 R5F101GAANA#W0, R5F101GCANA#W0, R5F101GDANA#W0, R5F101GEANA#W0, R5F101GFANA#W0, R5F101GGANA#W0, R5F101GHANA#W0, R5F101GJANA#W0, R5F101GKANA#W0, R5F101GLANA#W0
			D	R5F101GADNA#U0, R5F101GCDNA#U0, R5F101GDDNA#U0, R5F101GEDNA#U0, R5F101GFDNA#U0, R5F101GGDNA#U0, R5F101GHDNA#U0, R5F101GJDNA#U0, R5F101GKDNA#U0, R5F101GLDNA#U0 R5F101GADNA#W0, R5F101GCDNA#W0, R5F101GDDNA#W0, R5F101GEDNA#W0, R5F101GFDNA#W0, R5F101GGDNA#W0, R5F101GHDNA#W0, R5F101GJDNA#W0, R5F101GKDNA#W0, R5F101GLDNA#W0

**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13.**

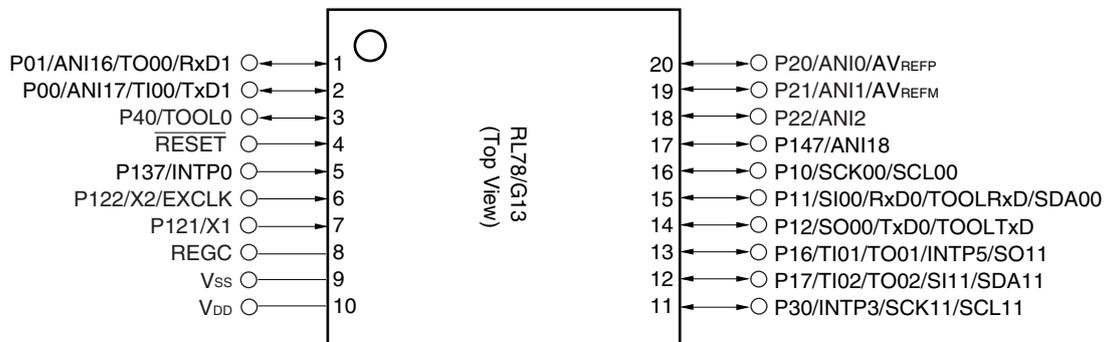
**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.



### 1.3 Pin Configuration (Top View)

#### 1.3.1 20-pin products

- 20-pin plastic LSSOP (7.62 mm (300), 0.65 mm pitch)



**Caution** Connect the REGC pin to V<sub>SS</sub> via a capacitor (0.47 to 1  $\mu$ F).

**Remark** For pin identification, see 1.4 Pin Identification.

## 1.4 Pin Identification

ANI0 to ANI14,		REGC:	Regulator capacitance
ANI16 to ANI26:	Analog input	RESET:	Reset
AV <sub>REFM</sub> :	A/D converter reference potential (– side) input	RTC1HZ:	Real-time clock correction clock (1 Hz) output
AV <sub>REFP</sub> :	A/D converter reference potential (+ side) input	RxD0 to RxD3:	Receive data
EV <sub>DD0</sub> , EV <sub>DD1</sub> :	Power supply for port	SCK00, SCK01, SCK10, SCK11, SCK20, SCK21,	
EV <sub>SS0</sub> , EV <sub>SS1</sub> :	Ground for port	SCLA0, SCLA1:	Serial clock input/output
EXCLK:	External clock input (Main system clock)	SCLA0, SCLA1, SCL00, SCL01, SCL10, SCL11,	
EXCLKS:	External clock input (Subsystem clock)	SCL20, SCL21, SCL30, SCL31:	Serial clock output
INTP0 to INTP11:	Interrupt request from peripheral	SDAA0, SDAA1, SDA00, SDA01, SDA10, SDA11, SDA20, SDA21, SDA30,	
KR0 to KR7:	Key return	SDA31:	Serial data input/output
P00 to P07:	Port 0	SI00, SI01, SI10, SI11,	
P10 to P17:	Port 1	SI20, SI21, SI30, SI31:	Serial data input
P20 to P27:	Port 2	SO00, SO01, SO10,	
P30 to P37:	Port 3	SO11, SO20, SO21,	
P40 to P47:	Port 4	SO30, SO31:	Serial data output
P50 to P57:	Port 5	TI00 to TI07,	
P60 to P67:	Port 6	TI10 to TI17:	Timer input
P70 to P77:	Port 7	TO00 to TO07,	
P80 to P87:	Port 8	TO10 to TO17:	Timer output
P90 to P97:	Port 9	TOOL0:	Data input/output for tool
P100 to P106:	Port 10	TOOLRxD, TOOLTxD:	Data input/output for external device
P110 to P117:	Port 11	TxD0 to TxD3:	Transmit data
P120 to P127:	Port 12	V <sub>DD</sub> :	Power supply
P130, P137:	Port 13	V <sub>SS</sub> :	Ground
P140 to P147:	Port 14	X1, X2:	Crystal oscillator (main system clock)
P150 to P156:	Port 15	XT1, XT2:	Crystal oscillator (subsystem clock)
PCLBUZ0, PCLBUZ1:	Programmable clock output/buzzer output		

[80-pin, 100-pin, 128-pin products]

**Caution** This outline describes the functions at the time when Peripheral I/O redirection register (PIOR) is set to 00H.

(1/2)

Item		80-pin		100-pin		128-pin	
		R5F100Mx	R5F101Mx	R5F100Px	R5F101Px	R5F100Sx	R5F101Sx
Code flash memory (KB)		96 to 512		96 to 512		192 to 512	
Data flash memory (KB)		8	–	8	–	8	–
RAM (KB)		8 to 32 <sup>Note 1</sup>		8 to 32 <sup>Note 1</sup>		16 to 32 <sup>Note 1</sup>	
Address space		1 MB					
Main system clock	High-speed system clock	X1 (crystal/ceramic) oscillation, external main system clock input (EXCLK) HS (High-speed main) mode: 1 to 20 MHz ( $V_{DD} = 2.7$ to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz ( $V_{DD} = 2.4$ to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz ( $V_{DD} = 1.8$ to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz ( $V_{DD} = 1.6$ to 5.5 V)					
	High-speed on-chip oscillator	HS (High-speed main) mode: 1 to 32 MHz ( $V_{DD} = 2.7$ to 5.5 V), HS (High-speed main) mode: 1 to 16 MHz ( $V_{DD} = 2.4$ to 5.5 V), LS (Low-speed main) mode: 1 to 8 MHz ( $V_{DD} = 1.8$ to 5.5 V), LV (Low-voltage main) mode: 1 to 4 MHz ( $V_{DD} = 1.6$ to 5.5 V)					
Subsystem clock		XT1 (crystal) oscillation, external subsystem clock input (EXCLKS) 32.768 kHz					
Low-speed on-chip oscillator		15 kHz (TYP.)					
General-purpose register		(8-bit register × 8) × 4 banks					
Minimum instruction execution time		0.03125 $\mu$ s (High-speed on-chip oscillator: $f_{IH} = 32$ MHz operation)					
		0.05 $\mu$ s (High-speed system clock: $f_{MX} = 20$ MHz operation)					
		30.5 $\mu$ s (Subsystem clock: $f_{SUB} = 32.768$ kHz operation)					
Instruction set		<ul style="list-style-type: none"> <li>Data transfer (8/16 bits)</li> <li>Adder and subtractor/logical operation (8/16 bits)</li> <li>Multiplication (8 bits × 8 bits)</li> <li>Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc.</li> </ul>					
I/O port	Total	74		92		120	
	CMOS I/O	64 (N-ch O.D. I/O [ $E_{VDD}$ withstand voltage]: 21)		82 (N-ch O.D. I/O [ $E_{VDD}$ withstand voltage]: 24)		110 (N-ch O.D. I/O [ $E_{VDD}$ withstand voltage]: 25)	
	CMOS input	5		5		5	
	CMOS output	1		1		1	
	N-ch O.D. I/O (withstand voltage: 6 V)	4		4		4	
Timer	16-bit timer	12 channels		12 channels		16 channels	
	Watchdog timer	1 channel		1 channel		1 channel	
	Real-time clock (RTC)	1 channel		1 channel		1 channel	
	12-bit interval timer (IT)	1 channel		1 channel		1 channel	
	Timer output	12 channels (PWM outputs: 10 <sup>Note 2</sup> )		12 channels (PWM outputs: 10 <sup>Note 2</sup> )		16 channels (PWM outputs: 14 <sup>Note 2</sup> )	
	RTC output	1 channel • 1 Hz (subsystem clock: $f_{SUB} = 32.768$ kHz)					

**Notes 1.** The flash library uses RAM in self-programming and rewriting of the data flash memory.

The target products and start address of the RAM areas used by the flash library are shown below.

R5F100xJ, R5F101xJ (x = M, P): Start address FAF00H

R5F100xL, R5F101xL (x = M, P, S): Start address F7F00H

For the RAM areas used by the flash library, see **Self RAM list of Flash Self-Programming Library for RL78 Family (R20UT2944)**.

## 2.2 Oscillator Characteristics

### 2.2.1 X1, XT1 oscillator characteristics

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = 0 V)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f <sub>x</sub> ) <sup>Note</sup>	Ceramic resonator/ crystal resonator	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	1.0		20.0	MHz
		2.4 V ≤ V <sub>DD</sub> < 2.7 V	1.0		16.0	MHz
		1.8 V ≤ V <sub>DD</sub> < 2.4 V	1.0		8.0	MHz
		1.6 V ≤ V <sub>DD</sub> < 1.8 V	1.0		4.0	MHz
XT1 clock oscillation frequency (f <sub>x</sub> ) <sup>Note</sup>	Crystal resonator		32	32.768	35	kHz

**Note** Indicates only permissible oscillator frequency ranges. Refer to AC Characteristics for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

**Caution** Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

**Remark** When using the X1 oscillator and XT1 oscillator, refer to 5.4 System Clock Oscillator.

### 2.2.2 On-chip oscillator characteristics

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = 0 V)

Oscillators	Parameters	Conditions		MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency <sup>Notes 1, 2</sup>	f <sub>IH</sub>			1		32	MHz
High-speed on-chip oscillator clock frequency accuracy		-20 to +85 °C	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	-1.0		+1.0	%
			1.6 V ≤ V <sub>DD</sub> < 1.8 V	-5.0		+5.0	%
		-40 to -20 °C	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	-1.5		+1.5	%
			1.6 V ≤ V <sub>DD</sub> < 1.8 V	-5.5		+5.5	%
Low-speed on-chip oscillator clock frequency	f <sub>IL</sub>				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				-15		+15	%

**Notes 1.** High-speed on-chip oscillator frequency is selected by bits 0 to 3 of option byte (000C2H/010C2H) and bits 0 to 2 of HOCODIV register.

**2.** This indicates the oscillator characteristics only. Refer to AC Characteristics for instruction execution time.

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ E<sub>VDD0</sub> = E<sub>VDD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = E<sub>VSS0</sub> = E<sub>VSS1</sub> = 0 V) (5/5)

Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
Input leakage current, high	I <sub>LIH1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VDD0</sub>		1	μA		
	I <sub>LIH2</sub>	P20 to P27, P137, P150 to P156, RESET	V <sub>I</sub> = V <sub>DD</sub>		1	μA		
	I <sub>LIH3</sub>	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	V <sub>I</sub> = V <sub>DD</sub>		In input port or external clock input	1	μA	
			In resonator connection	10	μA			
Input leakage current, low	I <sub>LIL1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VSS0</sub>		-1	μA		
	I <sub>LIL2</sub>	P20 to P27, P137, P150 to P156, RESET	V <sub>I</sub> = V <sub>SS</sub>		-1	μA		
	I <sub>LIL3</sub>	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	V <sub>I</sub> = V <sub>SS</sub>		In input port or external clock input	-1	μA	
			In resonator connection	-10	μA			
On-chip pll-up resistance	R <sub>U</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VSS0</sub> , In input port		10	20	100	kΩ

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

## 2.4 AC Characteristics

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Instruction cycle (minimum instruction execution time)	T <sub>CY</sub>	Main system clock (f <sub>MAIN</sub> ) operation	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125		1	μs
				2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625		1	μs
			LS (low-speed main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.125		1	μs
			LV (low-voltage main) mode	1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.25		1	μs
		Subsystem clock (f <sub>SUB</sub> ) operation		1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	28.5	30.5	31.3	μs
		In the self programming mode	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125		1	μs
				2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625		1	μs
			LS (low-speed main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.125		1	μs
			LV (low-voltage main) mode	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.25		1	μs
		External system clock frequency	f <sub>EX</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		1.0		20.0
2.4 V ≤ V <sub>DD</sub> < 2.7 V				1.0		16.0	MHz	
1.8 V ≤ V <sub>DD</sub> < 2.4 V				1.0		8.0	MHz	
1.6 V ≤ V <sub>DD</sub> < 1.8 V				1.0		4.0	MHz	
f <sub>EXS</sub>			32		35	kHz		
External system clock input high-level width, low-level width	t <sub>EXH</sub> , t <sub>EXL</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		24			ns	
		2.4 V ≤ V <sub>DD</sub> < 2.7 V		30			ns	
		1.8 V ≤ V <sub>DD</sub> < 2.4 V		60			ns	
		1.6 V ≤ V <sub>DD</sub> < 1.8 V		120			ns	
	t <sub>EXHS</sub> , t <sub>EXLS</sub>			13.7			μs	
TI00 to TI07, TI10 to TI17 input high-level width, low-level width	t <sub>TIH</sub> , t <sub>TIL</sub>			1/f <sub>MCK</sub> +10			ns <sup>Note</sup>	
TO00 to TO07, TO10 to TO17 output frequency	f <sub>TO</sub>	HS (high-speed main) mode	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			16	MHz	
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V			8	MHz	
			1.8 V ≤ EV <sub>DD0</sub> < 2.7 V			4	MHz	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V			2	MHz	
		LS (low-speed main) mode	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			4	MHz	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V			2	MHz	
		LV (low-voltage main) mode	1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			2	MHz	
PCLBUZ0, PCLBUZ1 output frequency	f <sub>PCL</sub>	HS (high-speed main) mode	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			16	MHz	
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V			8	MHz	
			1.8 V ≤ EV <sub>DD0</sub> < 2.7 V			4	MHz	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V			2	MHz	
		LS (low-speed main) mode	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			4	MHz	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V			2	MHz	
		LV (low-voltage main) mode	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			4	MHz	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V			2	MHz	
Interrupt input high-level width, low-level width	t <sub>INTH</sub> , t <sub>INTL</sub>	INTP0	1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	1			μs	
		INTP1 to INTP11	1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	1			μs	
Key interrupt input low-level width	t <sub>KR</sub>	KR0 to KR7	1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	250			ns	
			1.6 V ≤ EV <sub>DD0</sub> < 1.8 V	1			μs	
RESET low-level width	t <sub>RSL</sub>			10			μs	

(Note and Remark are listed on the next page.)

**(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2)****(T<sub>A</sub> = -40 to +85°C, 1.8 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit		
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.			
Transfer rate		Reception	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1	bps	
					5.3		1.3		0.6	Mbps	
			Theoretical value of the maximum transfer rate f <sub>MCK</sub> = f <sub>CLK</sub> <sup>Note 4</sup>								
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1		f <sub>MCK</sub> /6 Note 1	bps	
					5.3		1.3		0.6	Mbps	
			Theoretical value of the maximum transfer rate f <sub>MCK</sub> = f <sub>CLK</sub> <sup>Note 4</sup>								
1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V		f <sub>MCK</sub> /6 Notes 1 to 3		f <sub>MCK</sub> /6 Notes 1, 2		f <sub>MCK</sub> /6 Notes 1, 2	bps				
		5.3		1.3		0.6	Mbps				
Theoretical value of the maximum transfer rate f <sub>MCK</sub> = f <sub>CLK</sub> <sup>Note 4</sup>											

**Notes 1.** Transfer rate in the SNOOZE mode is 4800 bps only.**2.** Use it with EV<sub>DD0</sub> ≥ V<sub>b</sub>.**3.** The following conditions are required for low voltage interface when EV<sub>DD0</sub> < V<sub>DD</sub>.2.4 V ≤ EV<sub>DD0</sub> < 2.7 V : MAX. 2.6 Mbps1.8 V ≤ EV<sub>DD0</sub> < 2.4 V : MAX. 1.3 Mbps**4.** The maximum operating frequencies of the CPU/peripheral hardware clock (f<sub>CLK</sub>) are:HS (high-speed main) mode: 32 MHz (2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V)16 MHz (2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V)LS (low-speed main) mode: 8 MHz (1.8 V ≤ V<sub>DD</sub> ≤ 5.5 V)LV (low-voltage main) mode: 4 MHz (1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V)

**Caution** Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V<sub>DD</sub> tolerance (When 20- to 52-pin products)/EV<sub>DD</sub> tolerance (When 64- to 128-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V<sub>IH</sub> and V<sub>IL</sub>, see the DC characteristics with TTL input buffer selected.

**Remarks 1.** V<sub>b</sub>[V]: Communication line voltage**2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)**3.** f<sub>MCK</sub>: Serial array unit operation clock frequency(Operation clock to be set by the CKS<sub>mn</sub> bit of serial mode register mn (SMR<sub>mn</sub>). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))**4.** UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.

**(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)**  
**(3/3)****(T<sub>A</sub> = -40 to +85°C, 1.8 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)**

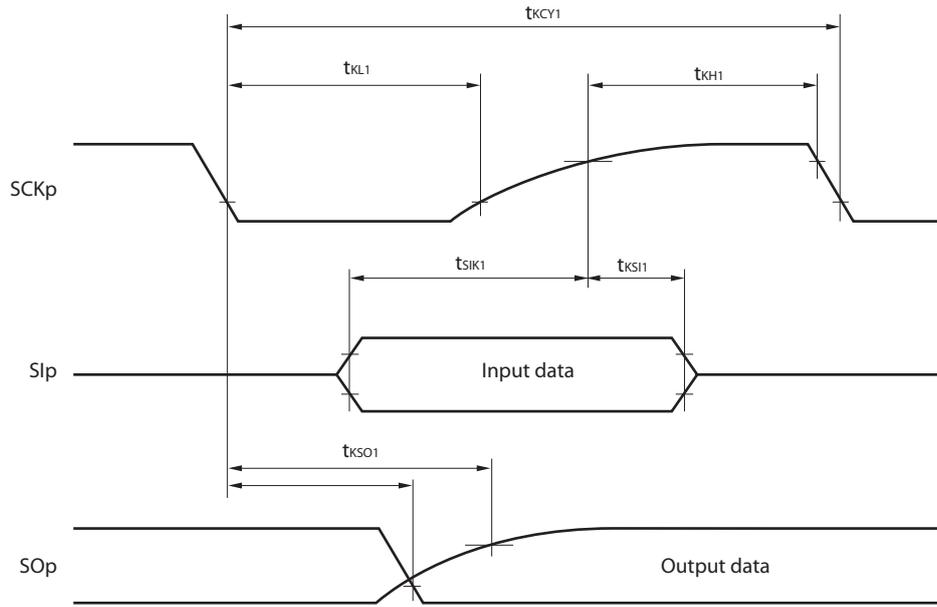
Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Slp setup time (to SCKp↓) <sup>Note 1</sup>	t <sub>SIK1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 1.4 kΩ	44		110		110		ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 2.7 kΩ	44		110		110		ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup> , C <sub>b</sub> = 30 pF, R <sub>b</sub> = 5.5 kΩ	110		110		110		ns
Slp hold time (from SCKp↓) <sup>Note 1</sup>	t <sub>KSH1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 1.4 kΩ	19		19		19		ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 2.7 kΩ	19		19		19		ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup> , C <sub>b</sub> = 30 pF, R <sub>b</sub> = 5.5 kΩ	19		19		19		ns
Delay time from SCKp↑ to SOp output <sup>Note 1</sup>	t <sub>KSO1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 1.4 kΩ		25		25		25	ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 30 pF, R <sub>b</sub> = 2.7 kΩ		25		25		25	ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup> , C <sub>b</sub> = 30 pF, R <sub>b</sub> = 5.5 kΩ		25		25		25	ns

- Notes**
1. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  2. Use it with EV<sub>DD0</sub> ≥ V<sub>b</sub>.

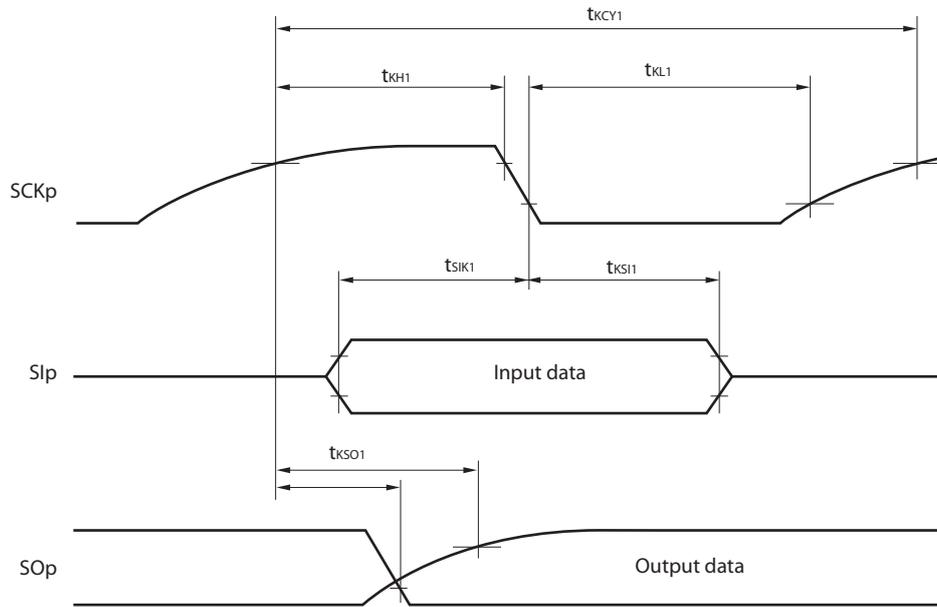
**Caution** Select the TTL input buffer for the Slp pin and the N-ch open drain output (V<sub>DD</sub> tolerance (When 20- to 52-pin products)/EV<sub>DD</sub> tolerance (When 64- to 128-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V<sub>IH</sub> and V<sub>IL</sub>, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)**



**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**



- Remarks 1.** p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number, n: Channel number (mn = 00, 01, 02, 10, 12, 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)
- 2.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

**(9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)****(T<sub>A</sub> = -40 to +85°C, 1.8 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V) (1/2)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time <sup>Note 1</sup>	t <sub>KCY2</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V	24 MHz < f <sub>MCK</sub>	14/ f <sub>MCK</sub>		—		—	ns
			20 MHz < f <sub>MCK</sub> ≤ 24 MHz	12/ f <sub>MCK</sub>		—		—	ns
			8 MHz < f <sub>MCK</sub> ≤ 20 MHz	10/ f <sub>MCK</sub>		—		—	ns
			4 MHz < f <sub>MCK</sub> ≤ 8 MHz	8/f <sub>MCK</sub>		16/ f <sub>MCK</sub>		—	ns
			f <sub>MCK</sub> ≤ 4 MHz	6/f <sub>MCK</sub>		10/ f <sub>MCK</sub>		10/ f <sub>MCK</sub>	ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V	24 MHz < f <sub>MCK</sub>	20/ f <sub>MCK</sub>		—		—	ns
			20 MHz < f <sub>MCK</sub> ≤ 24 MHz	16/ f <sub>MCK</sub>		—		—	ns
			16 MHz < f <sub>MCK</sub> ≤ 20 MHz	14/ f <sub>MCK</sub>		—		—	ns
			8 MHz < f <sub>MCK</sub> ≤ 16 MHz	12/ f <sub>MCK</sub>		—		—	ns
			4 MHz < f <sub>MCK</sub> ≤ 8 MHz	8/f <sub>MCK</sub>		16/ f <sub>MCK</sub>		—	ns
			f <sub>MCK</sub> ≤ 4 MHz	6/f <sub>MCK</sub>		10/ f <sub>MCK</sub>		10/ f <sub>MCK</sub>	ns
		1.8 V ≤ EV <sub>DD0</sub> < 3.3 V, 1.6 V ≤ V <sub>b</sub> ≤ 2.0 V <sup>Note 2</sup>	24 MHz < f <sub>MCK</sub>	48/ f <sub>MCK</sub>		—		—	ns
			20 MHz < f <sub>MCK</sub> ≤ 24 MHz	36/ f <sub>MCK</sub>		—		—	ns
			16 MHz < f <sub>MCK</sub> ≤ 20 MHz	32/ f <sub>MCK</sub>		—		—	ns
			8 MHz < f <sub>MCK</sub> ≤ 16 MHz	26/ f <sub>MCK</sub>		—		—	ns
			4 MHz < f <sub>MCK</sub> ≤ 8 MHz	16/ f <sub>MCK</sub>		16/ f <sub>MCK</sub>		—	ns
			f <sub>MCK</sub> ≤ 4 MHz	10/ f <sub>MCK</sub>		10/ f <sub>MCK</sub>		10/ f <sub>MCK</sub>	ns

(Notes and Caution are listed on the next page, and Remarks are listed on the page after the next page.)

### 3.3.2 Supply current characteristics

#### (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ ,  $V_{SS} = V_{SS0} = 0\text{ V}$ ) (1/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit	
Supply current Note 1	I <sub>DD1</sub>	Operating mode	HS (high-speed main) mode Note 5	$f_{IH} = 32\text{ MHz}$ <sup>Note 3</sup>	Basic operation	$V_{DD} = 5.0\text{ V}$		2.1		mA
						$V_{DD} = 3.0\text{ V}$		2.1		mA
				Normal operation	$V_{DD} = 5.0\text{ V}$		4.6	7.5	mA	
					$V_{DD} = 3.0\text{ V}$		4.6	7.5	mA	
				$f_{IH} = 24\text{ MHz}$ <sup>Note 3</sup>	Normal operation	$V_{DD} = 5.0\text{ V}$		3.7	5.8	mA
						$V_{DD} = 3.0\text{ V}$		3.7	5.8	mA
			HS (high-speed main) mode Note 5	$f_{MX} = 20\text{ MHz}$ <sup>Note 2</sup> , $V_{DD} = 5.0\text{ V}$	Normal operation	Square wave input		3.0	4.9	mA
						Resonator connection		3.2	5.0	mA
				$f_{MX} = 20\text{ MHz}$ <sup>Note 2</sup> , $V_{DD} = 3.0\text{ V}$	Normal operation	Square wave input		3.0	4.9	mA
						Resonator connection		3.2	5.0	mA
			$f_{MX} = 10\text{ MHz}$ <sup>Note 2</sup> , $V_{DD} = 5.0\text{ V}$	Normal operation	Square wave input		1.9	2.9	mA	
					Resonator connection		1.9	2.9	mA	
		$f_{MX} = 10\text{ MHz}$ <sup>Note 2</sup> , $V_{DD} = 3.0\text{ V}$	Normal operation	Square wave input		1.9	2.9	mA		
				Resonator connection		1.9	2.9	mA		
		Subsystem clock operation		$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = -40^\circ\text{C}$	Normal operation	Square wave input		4.1	4.9	$\mu\text{A}$
						Resonator connection		4.2	5.0	$\mu\text{A}$
				$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = +25^\circ\text{C}$	Normal operation	Square wave input		4.1	4.9	$\mu\text{A}$
						Resonator connection		4.2	5.0	$\mu\text{A}$
				$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = +50^\circ\text{C}$	Normal operation	Square wave input		4.2	5.5	$\mu\text{A}$
						Resonator connection		4.3	5.6	$\mu\text{A}$
$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = +70^\circ\text{C}$	Normal operation			Square wave input		4.3	6.3	$\mu\text{A}$		
				Resonator connection		4.4	6.4	$\mu\text{A}$		
$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = +85^\circ\text{C}$	Normal operation	Square wave input		4.6	7.7	$\mu\text{A}$				
		Resonator connection		4.7	7.8	$\mu\text{A}$				
$f_{SUB} = 32.768\text{ kHz}$ Note 4 $T_A = +105^\circ\text{C}$	Normal operation	Square wave input		6.9	19.7	$\mu\text{A}$				
		Resonator connection		7.0	19.8	$\mu\text{A}$				

(Notes and Remarks are listed on the next page.)

- Notes**
1. Total current flowing into  $V_{DD}$  and  $EV_{DD0}$ , including the input leakage current flowing when the level of the input pin is fixed to  $V_{DD}$ ,  $EV_{DD0}$  or  $V_{SS}$ ,  $EV_{SS0}$ . The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  2. When high-speed on-chip oscillator and subsystem clock are stopped.
  3. When high-speed system clock and subsystem clock are stopped.
  4. When high-speed on-chip oscillator and high-speed system clock are stopped. When  $AMPHS1 = 1$  (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.  
HS (high-speed main) mode:  $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }32\text{ MHz}$   
 $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}@1\text{ MHz to }16\text{ MHz}$

- Remarks**
1.  $f_{MX}$ : High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  2.  $f_{IH}$ : High-speed on-chip oscillator clock frequency
  3.  $f_{SUB}$ : Subsystem clock frequency (XT1 clock oscillation frequency)
  4. Except subsystem clock operation, temperature condition of the TYP. value is  $T_A = 25^\circ\text{C}$

## 3.4 AC Characteristics

(TA = -40 to +105°C, 2.4 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

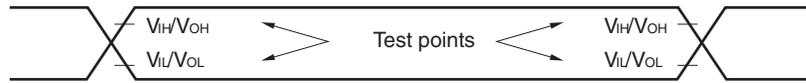
Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Instruction cycle (minimum instruction execution time)	T <sub>cy</sub>	Main system clock (f <sub>MAIN</sub> ) operation	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125		1	μs
				2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625		1	μs
		Subsystem clock (f <sub>SUB</sub> ) operation		2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	28.5	30.5	31.3	μs
		In the self programming mode	HS (high-speed main) mode	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.03125		1	μs
2.4 V ≤ V <sub>DD</sub> < 2.7 V	0.0625				1	μs		
External system clock frequency	f <sub>EX</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		1.0		20.0	MHz	
		2.4 V ≤ V <sub>DD</sub> < 2.7 V		1.0		16.0	MHz	
	f <sub>EXS</sub>			32		35	kHz	
External system clock input high-level width, low-level width	t <sub>EXH</sub> , t <sub>EXL</sub>	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V		24			ns	
		2.4 V ≤ V <sub>DD</sub> < 2.7 V		30			ns	
	t <sub>EXHS</sub> , t <sub>EXLS</sub>			13.7			μs	
Ti00 to Ti07, Ti10 to Ti17 input high-level width, low-level width	t <sub>TIH</sub> , t <sub>TIL</sub>			1/f <sub>MCK</sub> +10			ns <sup>Note</sup>	
TO00 to TO07, TO10 to TO17 output frequency	f <sub>TO</sub>	HS (high-speed main) mode	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			16	MHz	
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V			8	MHz	
			2.4 V ≤ EV <sub>DD0</sub> < 2.7 V			4	MHz	
PCLBUZ0, PCLBUZ1 output frequency	f <sub>PCL</sub>	HS (high-speed main) mode	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V			16	MHz	
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V			8	MHz	
			2.4 V ≤ EV <sub>DD0</sub> < 2.7 V			4	MHz	
Interrupt input high-level width, low-level width	t <sub>INTH</sub> , t <sub>INTL</sub>	INTP0	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	1			μs	
		INTP1 to INTP11	2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	1			μs	
Key interrupt input low-level width	t <sub>KR</sub>	KR0 to KR7	2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	250			ns	
RESET low-level width	t <sub>RSL</sub>			10			μs	

**Note** The following conditions are required for low voltage interface when  $EV_{DD0} < V_{DD}$   
 $2.4\text{ V} \leq EV_{DD0} < 2.7\text{ V}$  : MIN. 125 ns

**Remark** f<sub>MCK</sub>: Timer array unit operation clock frequency  
 (Operation clock to be set by the CKSmn0, CKSmn1 bits of timer mode register mn (TMRmn).  
 m: Unit number (m = 0, 1), n: Channel number (n = 0 to 7))

### 3.5 Peripheral Functions Characteristics

#### AC Timing Test Points



#### 3.5.1 Serial array unit

##### (1) During communication at same potential (UART mode)

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5\text{ V}$ ,  $V_{SS} = EV_{SS0} = EV_{SS1} = 0\text{ V}$ )

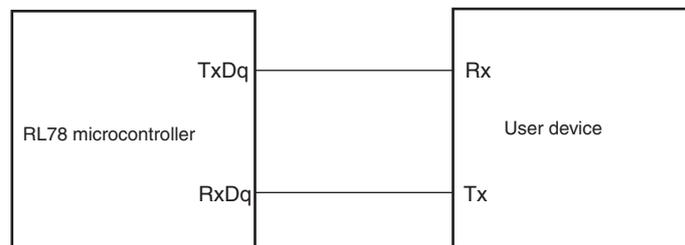
Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Transfer rate <sup>Note 1</sup>		Theoretical value of the maximum transfer rate $f_{CLK} = 32\text{ MHz}$ , $f_{MCK} = f_{CLK}$		$f_{MCK}/12$ <sup>Note 2</sup>	bps
				2.6	Mbps

**Notes 1.** Transfer rate in the SNOOZE mode is 4800 bps only.

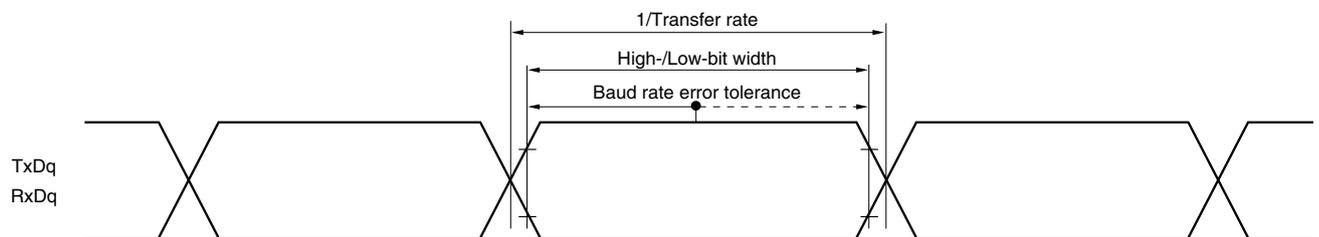
**2.** The following conditions are required for low voltage interface when  $EV_{DD0} < V_{DD}$ .  
 $2.4\text{ V} \leq EV_{DD0} < 2.7\text{ V}$  : MAX. 1.3 Mbps

**Caution** Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg).

#### UART mode connection diagram (during communication at same potential)



#### UART mode bit width (during communication at same potential) (reference)

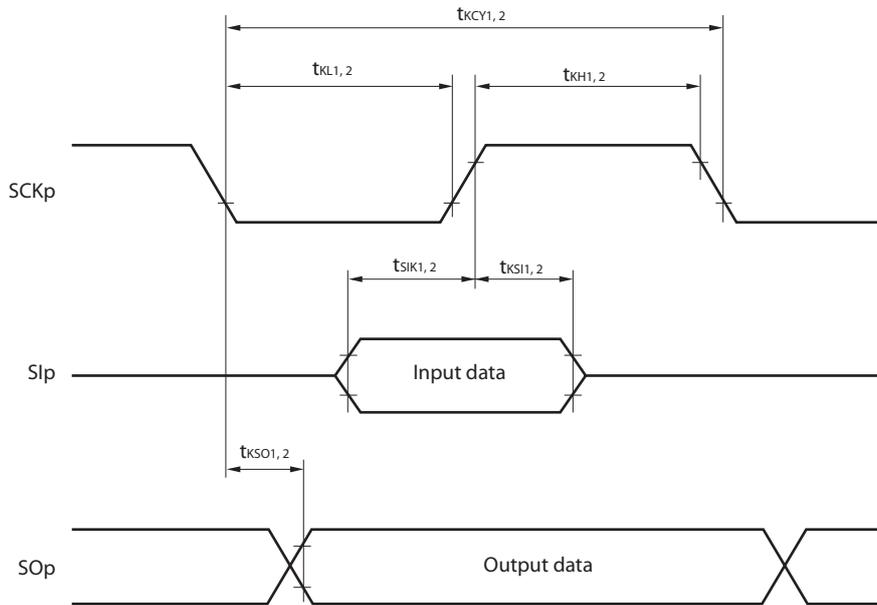


**Remarks 1.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)

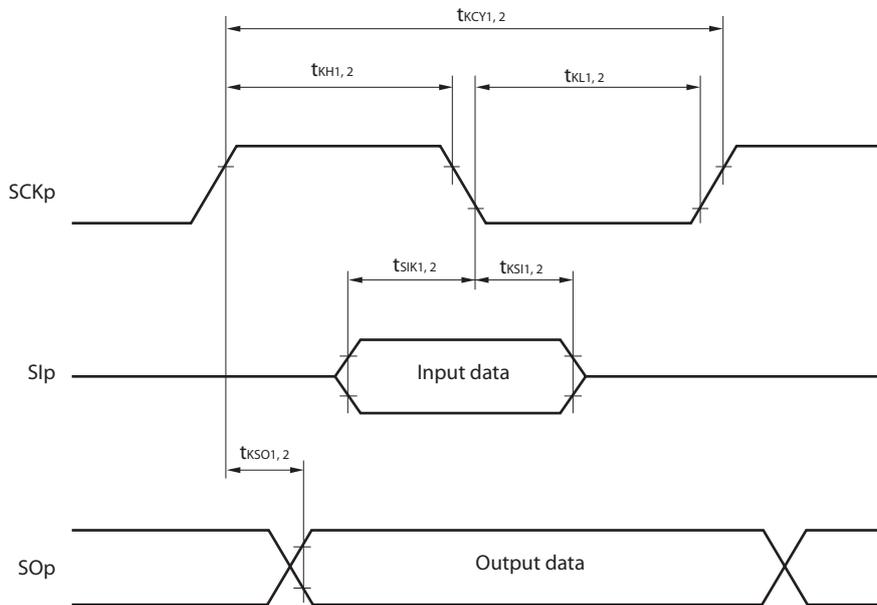
**2.**  $f_{MCK}$ : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

**CSI mode serial transfer timing (during communication at same potential)**  
**(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)**



**CSI mode serial transfer timing (during communication at same potential)**  
**(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**



- Remarks**
1. p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31)
  2. m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

5. The smaller maximum transfer rate derived by using  $f_{MCK}/12$  or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when  $2.4\text{ V} \leq EV_{DD0} < 3.3\text{ V}$  and  $1.6\text{ V} \leq V_b \leq 2.0\text{ V}$

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \text{ [bps]}$$

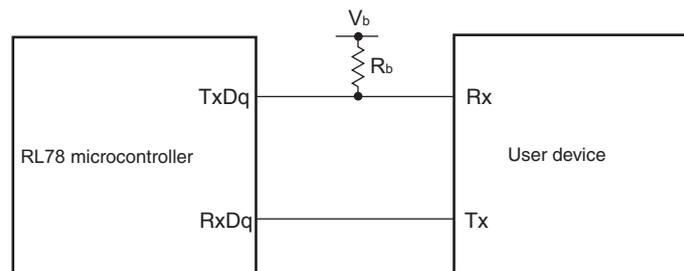
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [%]}$$

\* This value is the theoretical value of the relative difference between the transmission and reception sides.

6. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 5 above to calculate the maximum transfer rate under conditions of the customer.

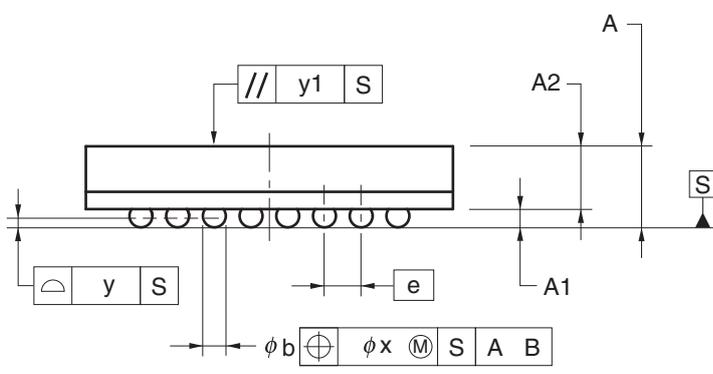
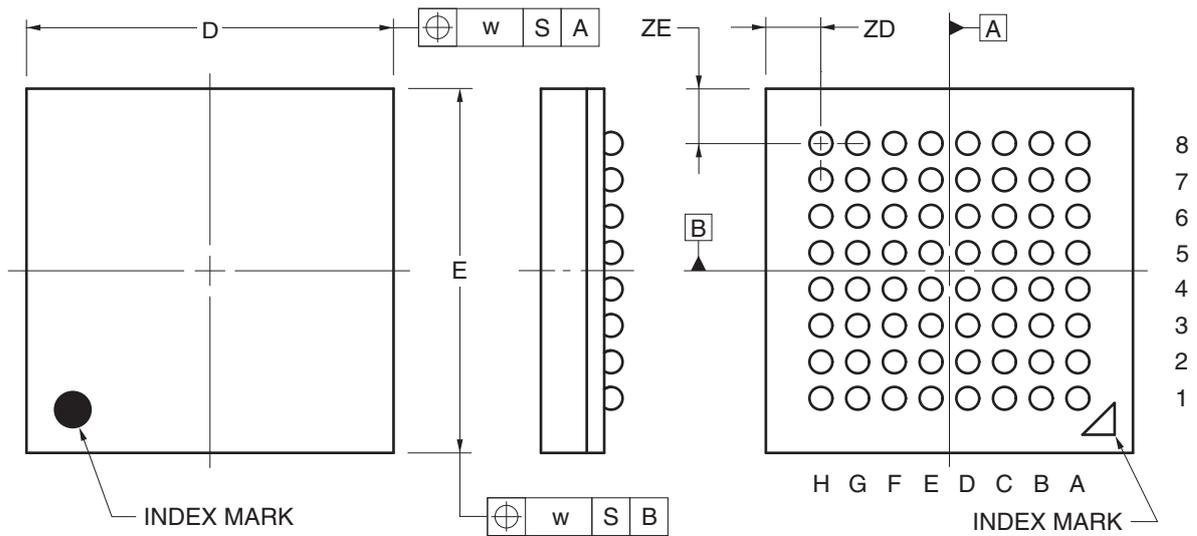
**Caution** Select the TTL input buffer for the RxDq pin and the N-ch open drain output ( $V_{DD}$  tolerance (for the 20- to 52-pin products)/ $EV_{DD}$  tolerance (for the 64- to 100-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For  $V_{IH}$  and  $V_{IL}$ , see the DC characteristics with TTL input buffer selected.

**UART mode connection diagram (during communication at different potential)**



R5F100LCABG, R5F100LDABG, R5F100LEABG, R5F100LFABG, R5F100LGABG, R5F100LHABG,  
 R5F100LJABG  
 R5F101LCABG, R5F101LDABG, R5F101LEABG, R5F101LFABG, R5F101LGABG, R5F101LHABG,  
 R5F101LJABG  
 R5F100LCGBG, R5F100LDGBG, R5F100LEGBG, R5F100LFGBG, R5F100LGGBG, R5F100LHGBG,  
 R5F100LJGBG

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-VFBGA64-4x4-0.40	PVBG0064LA-A	P64F1-40-AA2-2	0.03



(UNIT:mm)

ITEM	DIMENSIONS
D	4.00±0.10
E	4.00±0.10
w	0.15
A	0.89±0.10
A1	0.20±0.05
A2	0.69
e	0.40
b	0.25±0.05
x	0.05
y	0.08
y1	0.20
ZD	0.60
ZE	0.60

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<b>Revision History</b>	<b>RL78/G13 Data Sheet</b>
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Rev.	Date	Description	
		Page	Summary
1.00	Feb 29, 2012	-	First Edition issued
2.00	Oct 12, 2012	7	Figure 1-1. Part Number, Memory Size, and Package of RL78/G13: Pin count corrected.
		25	1.4 Pin Identification: Description of pins INTP0 to INTP11 corrected.
		40, 42, 44	1.6 Outline of Functions: Descriptions of Subsystem clock, Low-speed on-chip oscillator, and General-purpose register corrected.
		41, 43, 45	1.6 Outline of Functions: Lists of Descriptions changed.
		59, 63, 67	Descriptions of Note 8 in a table corrected.
		68	(4) Common to RL78/G13 all products: Descriptions of Notes corrected.
		69	2.4 AC Characteristics: Symbol of external system clock frequency corrected.
		96 to 98	2.6.1 A/D converter characteristics: Notes of overall error corrected.
		100	2.6.2 Temperature sensor characteristics: Parameter name corrected.
		104	2.8 Flash Memory Programming Characteristics: Incorrect descriptions corrected.
		116	3.10 52-pin products: Package drawings of 52-pin products corrected.
		120	3.12 80-pin products: Package drawings of 80-pin products corrected.
		3.00	Aug 02, 2013
3	Modification of 1.2 List of Part Numbers		
4 to 15	Modification of Table 1-1. List of Ordering Part Numbers, note, and caution		
16 to 32	Modification of package type in 1.3.1 to 1.3.14		
33	Modification of description in 1.4 Pin Identification		
48, 50, 52	Modification of caution, table, and note in 1.6 Outline of Functions		
55	Modification of description in table of Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ )		
57	Modification of table, note, caution, and remark in 2.2.1 X1, XT1 oscillator characteristics		
57	Modification of table in 2.2.2 On-chip oscillator characteristics		
58	Modification of note 3 of table (1/5) in 2.3.1 Pin characteristics		
59	Modification of note 3 of table (2/5) in 2.3.1 Pin characteristics		
63	Modification of table in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products		
64	Modification of notes 1 and 4 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products		
65	Modification of table in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products		
66	Modification of notes 1, 5, and 6 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products		
68	Modification of notes 1 and 4 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products		
70	Modification of notes 1, 5, and 6 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products		
72	Modification of notes 1 and 4 in (3) Flash ROM: 384 to 512 KB of 44- to 100-pin products		
74	Modification of notes 1, 5, and 6 in (3) Flash ROM: 384 to 512 KB of 44- to 100-pin products		
75	Modification of (4) Peripheral Functions (Common to all products)		
77	Modification of table in 2.4 AC Characteristics		
78, 79	Addition of Minimum Instruction Execution Time during Main System Clock Operation		
80	Modification of figures of AC Timing Test Points and External System Clock Timing		